

FEATURES

- LOW COST
- NON-CONDUCTIVE CASE
- INTERNAL INPUT AND OUTPUT FILTERING
- SHORT CIRCUIT PROTECTED
- BUILT-IN STANDOFFS
- INDUSTRY STANDARD PINOUT
- ROHS COMPLIANT

DESCRIPTION

The HL01RYC Series uses advanced circuit design and packaging technology to realize superior reliability and performance. A 125kHz push-pull oscillator is used in the input stage. Beat-frequency oscillator problems are reduced when using the HL01RYC Series with high frequency isolation amplifiers.

Reduced parts count and all surface mount construction add to the reliability of the HL01RYC Series. The use of surface mount devices and magnetics eliminate hand soldering operations. This "hands-free" construction increases quality and reliability while keeping cost low.

ABSOLUTE MAXIMUM RATINGS

Internal Power Dissipation.....	1.2W
Short Circuit Duration.....	Continuous*
Lead Temperature (soldering, 10 seconds max).....	+300°C*

* Note: Refer to Reflow Profile for SMD Models.

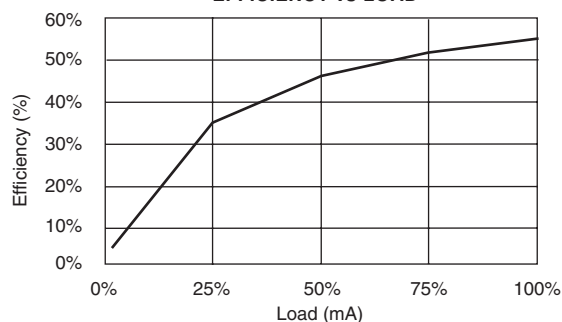
ORDERING INFORMATION

Device Family	HL01R	xx	yy	zz	Y	C
HL Indicates DC/DC Converter						
Model Number						
Where:						
xx = Input Voltage						
y = Number of Outputs (Single "S", Dual "D")						
zz = Output Voltage						
Package Option						
RoHS Compliant						

TYPICAL PERFORMANCE CURVES

Specifications typical at $T_A = +25^\circ\text{C}$, nominal input voltage, rated output current unless otherwise specified.

EFFICIENCY vs LOAD



For full details go to
www.murata-ps.com/rohs

ELECTRICAL SPECIFICATIONS

Specifications typical at $T_A = +25^{\circ}\text{C}$, nominal input voltage, rated output current unless otherwise specified.

MODEL	NOMINAL INPUT VOLTAGE (VDC)	RATED OUTPUT VOLTAGE (VDC)	RATED OUTPUT CURRENT (mA)	INPUT CURRENT		EFFICIENCY (%)
				MIN LOAD (mA)	RATED LOAD (mA)	
HL01R05S05YC	5	5	200	50	400	58
HL01R05S12YC	5	12	83	50	400	52
HL01R05S15YC	5	15	67	50	400	52
HL01R12S05YC	12	5	200	40	160	58
HL01R12S12YC	12	12	83	40	160	52
HL01R12S15YC	12	15	67	40	160	52
HL01R15S05YC	15	5	200	30	130	58
HL01R15S12YC	15	12	83	30	130	52
HL01R15S15YC	15	15	67	30	130	52
HL01R24S05YC	24	5	200	20	80	58
HL01R24S12YC	24	12	83	20	80	52
HL01R24S15YC	24	15	67	20	80	52
HL01R05D05YC	5	± 5	± 100	50	425	45
HL01R05D12YC	5	± 12	± 41	50	400	53
HL01R05D15YC	5	± 15	± 33	50	400	53
HL01R12D05YC	12	± 5	± 100	40	185	45
HL01R12D12YC	12	± 12	± 41	40	160	53
HL01R12D15YC	12	± 15	± 33	40	160	53
HL01R15D05YC	15	± 5	± 100	30	145	45
HL01R15D12YC	15	± 12	± 41	30	130	53
HL01R15D15YC	15	± 15	± 33	30	130	53
HL01R24D05YC	24	± 5	± 100	20	90	45
HL01R24D12YC	24	± 12	± 41	20	80	53
HL01R24D15YC	24	± 15	± 33	20	80	53

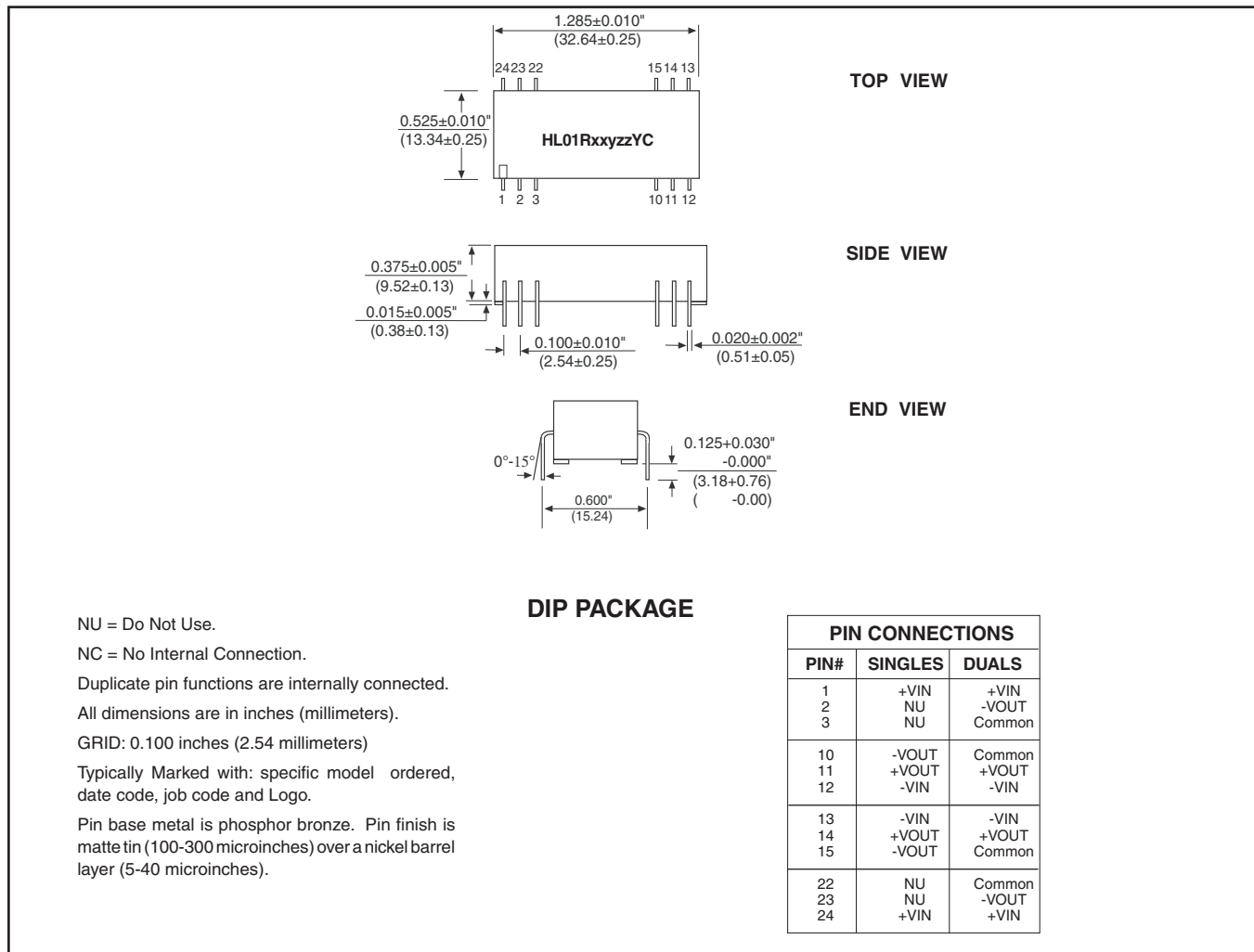
Note: Other input to output voltages may be available. Please contact factory.

COMMON SPECIFICATIONS

Specifications typical at $T_A = +25^{\circ}\text{C}$, nominal input voltage, rated output current unless otherwise specified.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
INPUT					
Voltage Range		4.75	5	5.25	VDC
		11.4	12	12.6	VDC
		14.25	15	15.75	VDC
Reflected Ripple Current		22.8	24	25.2	VDC
			30	100	mAp-p
ISOLATION					
Rated Voltage		500			VDC
Test Voltage	60 Hz, 10 Seconds	500			Vpk
Resistance			1		GΩ
Capacitance			25		pF
Leakage Current	$V_{ISO} = 240\text{VAC}$, 60Hz		2	10	μArms
OUTPUT					
Rated Power			1		W
Voltage Setpoint Accuracy			± 3	± 5	%
Temperature Coefficient			± 0.01	± 0.02	%/ $^{\circ}\text{C}$
Ripple & Noise	BW = DC to 10MHz		30	100	mVp-p
	BW = 10Hz to 2MHz		1	10	mVrms
Line Regulation	High Line to Low Line	± 0.1		± 1	%
Load Regulation	Rated Load to No Load	± 0.5		± 1	%
GENERAL					
Switching Frequency			125		kHz
Package Weight			10		g
MTTF per MIL-HDBK-217, Rev. F	Circuit Stress Method		675		kHr
Ground Benign			2		
Moisture Sensitivity Level (MSL)	IPC/JEDEC J-STD-20		2		
TEMPERATURE					
Specification		-25		+70	$^{\circ}\text{C}$
Operation		-40		+85	$^{\circ}\text{C}$
Storage		-40		+110	$^{\circ}\text{C}$

MECHANICAL Package/Pinout "Y"



THROUGH-HOLE SOLDERING INFORMATION

These devices are intended for wave soldering or manual soldering.

They are not intended to be subject to surface mount processes under any circumstances.

The normal wave soldering process can be used with these devices where the device is subjected to a maximum wave temperature of 260°C for a period of no more than 10 seconds. Within this time and temperature range, the integrity of the device's plastic body will not be compromised and internal temperatures within the converter will not exceed 175°C. Care should be taken to control manual soldering limits identical to that of wave soldering.